


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/18/10595	
1.3 Title of PCN	TSMC (Taiwan) additional source for STM32F427/9 & STM32F437/9 products in M10/90nm technology	
1.4 Product Category	STM32F427/9 & STM32F437/9 products in M10/90nm technology	
1.5 Issue date	2018-03-13	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	TSMC Fab14 (Taiwan)

4. Description of change

	Old	New
4.1 Description	Front-end source: - ST Crolles CRL300 (France) - ST Rousset 8" (France)	Front-end sources: - ST Crolles CRL300 (France) - Existing source - ST Rousset 8" (France) - Existing source - TSMC Fab14 (Taiwan) - Additional source - There is no change in the product functionality. Please refer to PCN 10595 – Additional information attached document.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible through diffusion traceability plant, in the marking: - "VQ" for ST Crolles CRL300 (France) - "VG" for ST Rousset 8" (France) - "9R" for TSMC Fab14 (Taiwan) Please refer to PCN 10595 – Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2018-06-22
7.2 Intended start of delivery	2018-06-22
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
8.1 Description	10595 MDG-MCD RER1715 PCN10333 - PCN10544 PCN10595 TSMC Taiwan.pptx		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-03-13

9. Attachments (additional documentations)
10595 Public product.pdf 10595 PCN10595_Division Note M10 Additional Source.pdf 10595 MDG-MCD RER1715 PCN10333 - PCN10544 PCN10595 TSMC Taiwan.pptx 10595 PCN10595_Additional information.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F427VGT7	
	STM32F429AIH6	
	STM32F437VIT6WTR	
	STM32F427IIT7	

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